

 Répondre  Répondre à tous  Transférer    Fermer  Aide

De: Eric Joseph Date: mer. 20/04/2011 22:07
Bertrand Clou; Alexandre Apcher; Berengere Le Men; Geraldine Saint Upery;
Hassan Chaoui; Stephanie Cambounet; Anissa Karray-Kbaier; Aurore Masson;
À: Fabien Foulon; Julien Clemens; Patrice Delpy; Virginie Duchemann; Christophe
Pinatel; Dominique Romeo; Marc Dos Santos; Marc Ryat; Pascal Tournier;
Stephane Colomines; Stephane Ramond; Steve Charpentier
Tim Gurnett; Brian Pickard; Darren Hooks; Monica Griffin; Stephen Dow; Martin
Cc: Kejhar; Jozef Kiss; Milan Valenta; Philippe Andre; Bob Boos; Lang Dinh; Renato
Golecruz; Josh Warner; David McDonald; Thibault Kassir; Simon Keeton
Objet : RE: NCS8381 Tape out done on time! :-)
Pièces jointes :

[Afficher sous forme de page Web](#)

Outstanding job. Thanks.

-----Original Message-----

From: Bertrand Clou

Sent: Wednesday, April 20, 2011 10:13 AM

To: Alexandre Apcher; Berengere Le Men; Geraldine Saint Upery; Hassan Chaoui; Stephanie Cambounet; Anissa Karray-Kbaier; Aurore Masson; Fabien Foulon; Julien Clemens; Patrice Delpy; Virginie Duchemann; Christophe Pinatel; Dominique Romeo; Marc Dos Santos; Marc Ryat; Pascal Tournier; Stephane Colomines; Stephane Ramond; Steve Charpentier

Cc: Tim Gurnett; Brian Pickard; Darren Hooks; Monica Griffin; Stephen Dow; Martin Kejhar; Jozef Kiss; Milan Valenta; Philippe Andre; Bob Boos; Lang Dinh; Renato Golecruz; Josh Warner; David McDonald; Thibault Kassir; Eric Joseph; Simon Keeton

Subject: NCS8381 Tape out done on time! :-)

Importance: High

All,

For your information, Dominique and Alexandre have just sent the gds of the reticule that contains the 8381

Congratulations to the audio team (Tlse and Austin), verification and Physical design teams (Tlse and Roznov) for their hard work to meet this key milestone for the NCS8381 project.

Thank you also to the rest of project team for their collaboration and support.

Regards,

Berengere & Bertrand

-----Original Message-----

From: Alexandre Apcher

Sent: Wednesday, April 20, 2011 6:27 PM

To: Berengere Le Men; 'zrhuang@tsmc.com'; Toby@ememory.com.tw

Cc: Tim Gurnett; Chris Gibson; 'EHAAS@tsmc.com'; 'GTHALLIKAR@tsmc.com'; 'JXYHUANG@tsmc.com';

'LZENGA@tsmc.com'; 'RWATERS@tsmc.com'; 'HHFAN@tsmc.com'; 'ALEEA@tsmc.com'; 'ems_manager@tsmc.com';

Dominique Romeo; Darren Hooks; Bertrand Clou

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Hello Zi-Ran, Hello Toby,

We have just submit the gds and the tape out form for the reticule TMEL64_C22 on the 27th april cybershuttle.

Find attached the die saw diagram updated.

Toby,

Find in attachment the IP merge forms fully completed.

As we use EO01x32KCT1 we don't fill the items 10 in IP Merge Notice request Form 2011. Please confirm that it s OK If you

encounter any trouble or if you have any questions, Please do not hesitate to contact: Tim gurnett, berengere Lemen, bertrand clou, alexandre apcher, dominique romeo (ONSEMI guys in copy of this mail).

Additional informations for the IP merge:

There are 4 dies on the reticule. Only 2 contains OTP eMemory IP.

Best Regards,
Alexandre Apcher

-----Original Message-----

From: Berengere Le Men

Sent: Monday, April 18, 2011 11:19 AM

To: zrhuang@tsmc.com

Cc: Tim Gurnett; Chris Gibson; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com;

LZENGGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems_manager@tsmc.com; Alexandre Apcher; Dominique Romeo; Darren Hooks

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Hello Zi-Ran,

We'll send it to you as soon as it's ready.

Best regards,
Berengere.

-----Original Message-----

From: zrhuang@tsmc.com [<mailto:zrhuang@tsmc.com>]

Sent: Monday, April 18, 2011 11:15 AM

To: Berengere Le Men

Cc: Tim Gurnett; Chris Gibson; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com;

LZENGGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems_manager@tsmc.com; Alexandre Apcher; Dominique Romeo; Darren Hooks; zrhuang@tsmc.com

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Dear Berengere,

Many thanks for your info.

Could you please provide the floor plan to me for extra die-saw availability checking since you require that ?

Thanks again ~

Below mail mentioned:

If your tape-out contains multiple designs and needs TSMC to do extra die-saw in order to singulate each sub-chip, please email the die-saw floor plan to me by 04/20/2011.

Thanks and best regards!

Zi-Ran (Nature) Huang 黃自然

CyberShuttle Service

Taiwan Semiconductor Manufacturing Company, Ltd.

No.121, Park Ave.3, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C

Tel: 886-3-5636688

Ext: 702-2199

zrhuang@tsmc.com

"Berengere Le

Men" To: <ZRHUANG@tsmc.com>

<Berengere.LeMen@ onsemi.com> cc: "Tim Gurnett" <Tim.Gurnett@onsemi.com>, "Chris Gibson"

<GTHALLIKAR@tsmc.com>, <Chris.Gibson@onsemi.com>, <EHAAS@tsmc.com>,

<JXYHUANG@tsmc.com>, <LZENGA@tsmc.com>, <RWATERS@tsmc.com>,
<HHFAN@tsmc.com>,

2011/04/18 05:07 <ALEEA@tsmc.com>, <ems_manager@tsmc.com>, "Alexandre
Apcher"

PM <Alexandre.Apcher@onsemi.com>, "Dominique Romeo"
<dominique.romeo@onsemi.com>,

"Darren Hooks" <Darren.Hooks@onsemi.com>

CyberShuttle Subject: RE: SECURITY C - ON [0.18 UM, TMEL64_C22, 04/27/2011]: Request

PO/Tape-out Form/GDS File

Hello Zi-Ran,

I would like to inform you that we will tape-out a reticule with 4 dies in total: 2 dies of 2160.0 um x 4160.0 um each, and 2 other dies of 1750um x 400um each.

Best regards,
Berengere.

-----Original Message-----

From: ZRHUANG@tsmc.com [<mailto:ZRHUANG@tsmc.com>]

Sent: Wednesday, April 13, 2011 9:55 AM

To: Darren Hooks

Cc: Tim Gurnett; Berengere Le Men; Chris Gibson; ZRHUANG@tsmc.com; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com; LZENGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems_manager@tsmc.com

Subject: SECURITY C - ON [0.18 UM, TMEL64_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Dear Darren Hooks

TMEL64 CyberShuttle is about to be launched. (Shuttle type: 0.18 UM CMOS High Voltage Mixed Signal based General Purpose BCD Dual Gate FSG AL 1P6M 1.8/5/18/24/32/40V Vg1.8/5V). Please use TMEL64_C22 as the TSMC Product Name for your device.

If your tape-out contains multiple designs and needs TSMC to do extra die-saw in order to singulate each sub-chip, please

email the die-saw floor plan to me by 04/20/2011.

By 04/27/2011 10:00AM Taiwan time (GMT +8), I need the following tape-in materials.

1. PO & Prepayment: Please send it to TSMC (ALEEA@tsmc.com) 2. GDS2

Database: Please put it under one of our FTP servers (e.g. ftp.tsmc.com.tw).

3. Tape-Out Form: Please fill out the form on TSMC-Online, submit it, and pass "DB Check". (To fill out the form, please access TSMC-Online > Business Transactions > CyberShuttle > Online Tape-Out Form > Create Tape-Out Form. After submitting the form, an auto DB Check program will check whether the Tape-Out Form complies with the GDS database, and email you the checking results shortly.

If your device needs TSMC to merge IP/library, please contact your account manager(EHAAS@tsmc.com, GTHALLIKAR@tsmc.com, JXYHUANG@tsmc.com, LZENGA@tsmc.com, RWATERS@tsmc.com) or customer service

manager(HHFAN@tsmc.com) in advance and send your GDS file to TSMC no later than 04/21/2011. Please remember to put the IP merged GDS file, but not the GDS before IP merge, on the tape-out form.

TSMC Product Name: TMEL64_C22

** Customer Tape-Out Information ** (Status : approved)

-
1. Resv No: 227437
 2. Tape-in Date: 04/27/2011
 3. Fab: FAB8B
 4. Geometry: 0.18 UM
 5. TM Number: TMEL64
 6. Shuttle Type: 0.18 UM CMOS High Voltage Mixed Signal based General Purpose BCD Dual Gate FSG AL 1P6M 1.8/5/18/24/32/40V Vg1.8/5V 7.

Customer Product Name: NCS8381 8. For which application is your design primarily intended? Consumer--Digital TV/HDTV 9. How many devices are included in this tape-out? 1 10. What do you use CyberShuttle for?

(Check all that apply) circuit characterizaion, IP verification, full chip verification, engineering samples 11. Is this tape-out a new design or a re-design? new design Please specify its previous device name:

12. When will be your follow-up new product at TSMC based on this shuttle verification result? 201109 13. #P#M: 1P6M 14. Chip Size: X = 2160.0 um, Y = 4100.0 um, Shrinkage = 100%, Blocks = 1.0

15. Bumping: No (Bumping needs NRE surcharge.)

16. RDL: No (RDL, redistribution layers for bumping process, needs NRE surcharge.)

17. Extra Die-Saw: Yes

18. Sample Quantity: Bare Dice 360 + Packaged Chips 0, Package Type: NONE

Extra Sub-chips: 0 Whole Sample Wafers: Yes, 1 piece(s) Extra Charged Wafers: 9 piece(s) 19. Split Condition: No 20. Need TSMC IP

Merge: Yes 21. Special Requests:

OTP None

22. Remarks: 1) Require MIM caps, HRI poly, UTM and OTP options.

2) Back grind wafers / die to 11 mils thickness

3) Full processing of first sawn 40 pc block + three wafers.

4) Hold remaining five wafers at pre-metal (prior to metal processing) in anticipation of future metal design modifications.

5) Request overnight shipment to: Mr. Tim Gurnett (602-244-4181); SCI LLC, 5005 E McDowell Rd, M/D E6100, Phoenix, Arizona, 85008, United States 23. Company Code: U797 24. Company Name: ON 25. Contact Person:

Darren Hooks 26. Email: darren.hooks@onsemi.com 27. TEL No: 602 244 6468 28. Email Cc:

tim.gurnett@onsemi.com,berengere.lemen@onsemi.com,chris.gibson@onsemi.com

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29. Account Manager Email: EHAAS@tsmc.com, GTHALLIKAR@tsmc.com, JXYHUANG@tsmc.com,

LZENGA@tsmc.com, RWATERS@tsmc.com 30. Customer Support Email: ALEEA@tsmc.com 31. Customer Service Manager Email:

HHFAN@tsmc.com 32. CyberShuttle Captain Email: ZRHUANG [ZRHUANG@tsmc.com] 33. TSMC Remarks:

IP Clarification: Please perform IP Clarification on TSMC-Online to prevent from using Problematic IP/Lib. (To perform IP Clarification, please access TSMC-Online > TapeOut & Mask Service > IP Clarification and follow the steps. After submitting the form, the IP Clarification report will be sent by email in 30 minutes.)

Sincerely yours,

TSMC CyberShuttle Team
Zi-Ran Huang

TSMC PROPERTY

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